

***W-LAN Module
for Mobile Applications
by LTCC Multilayer Technology***



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Introduction

- ✓ Various Components for W-LAN Application***
- ✓ LTCC Front End Module for 802.11b/g Application***
- ✓ LTCC 802.11b/g Module for Mobile Application***
- ✓ To solve critical issues with Multilayer technology***



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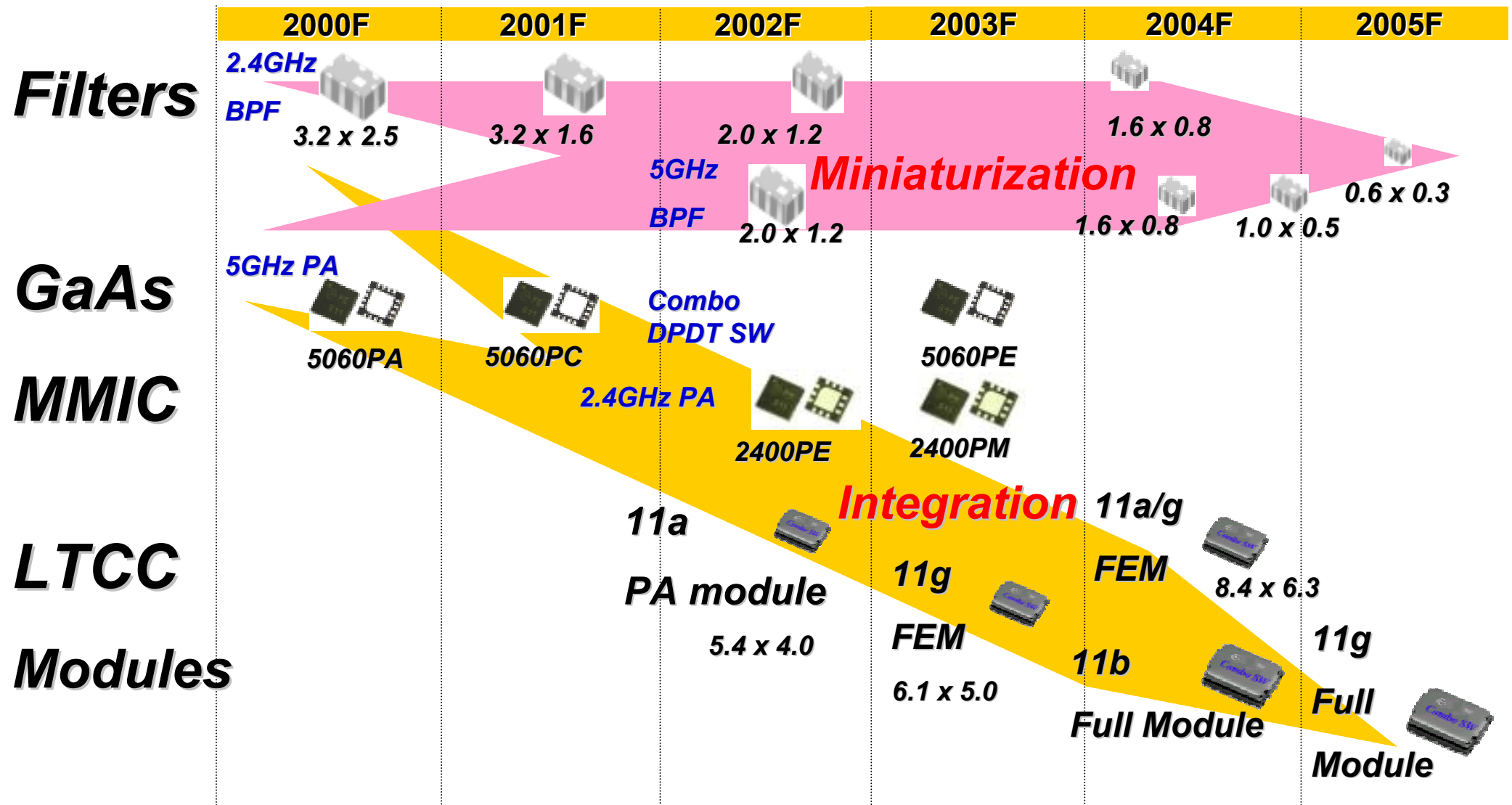
1st Topic

- ✓ ***Various Components for W-LAN Application***
- ✓ *LTCC Front End Module for 802.11b/g Application*
- ✓ *LTCC 802.11b/g Module for Mobile Application*
- ✓ *To solve critical issues with Multilayer technology*



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Various Devices for W-LAN



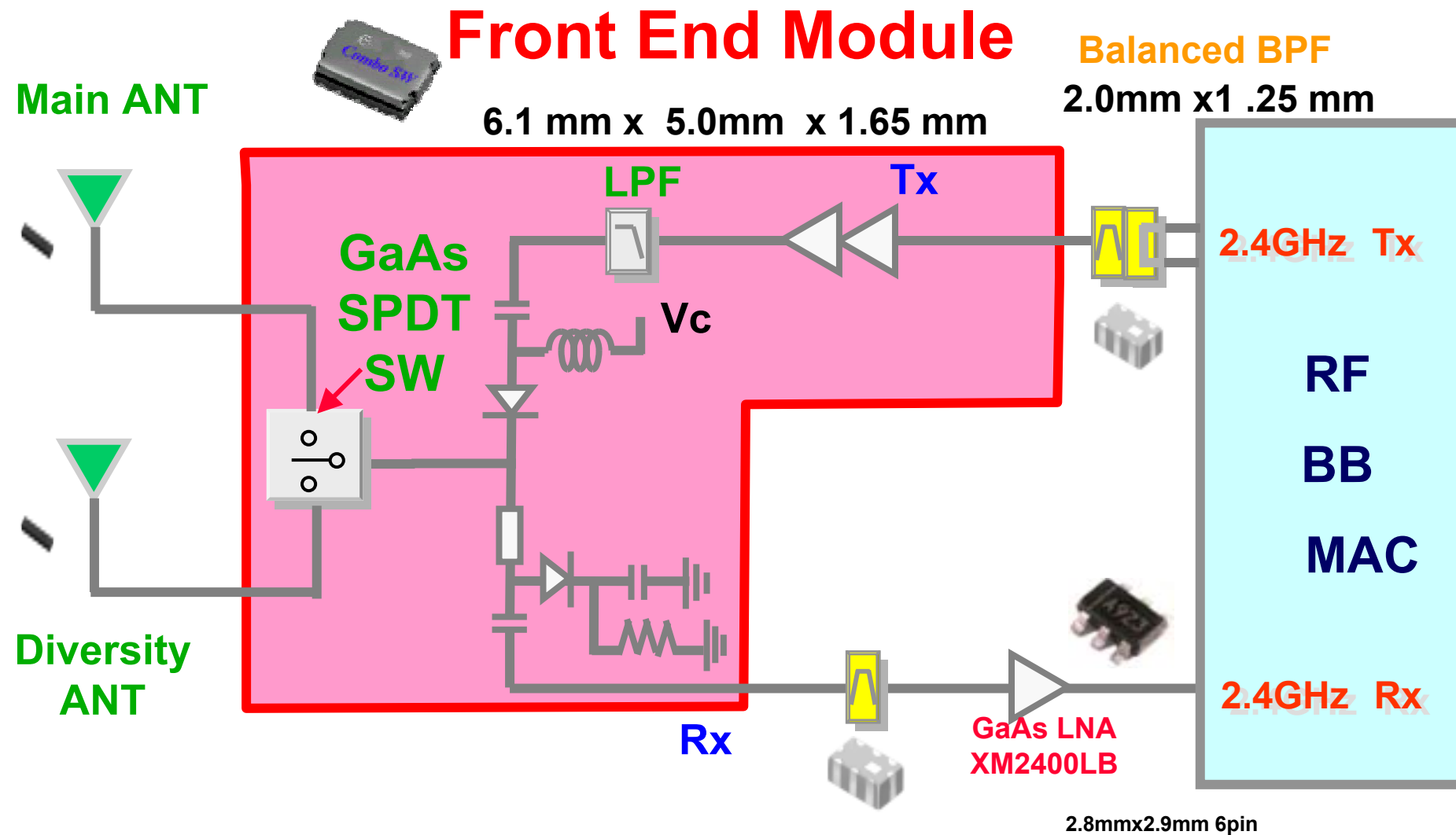
2nd Topic

- ✓ *Various Components for W-LAN Application*
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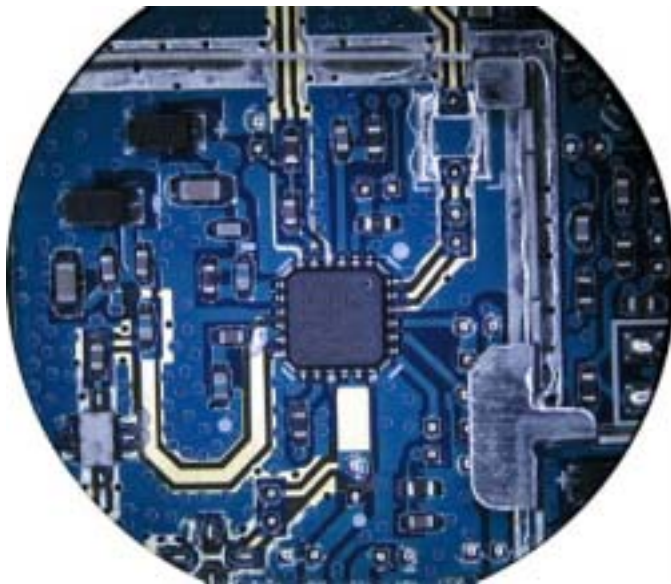
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LTCC Front End Module for .11b/g (1)

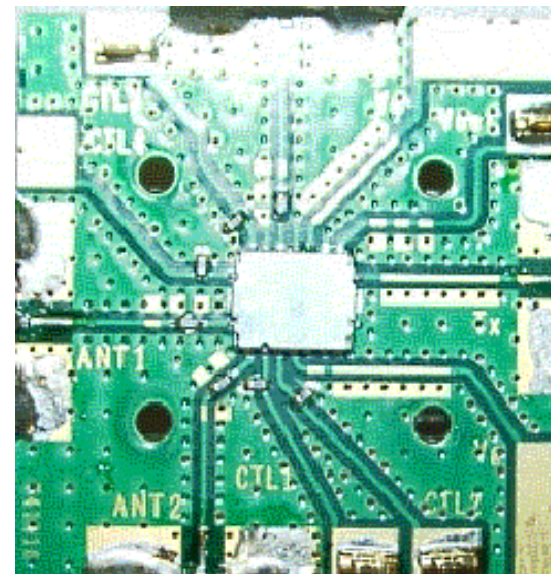


LTCC Front End Module for .11b/g (2)

Around PA



***FEM
(SW+PA+Filter)***



Simple and Small

6.1 mm x 5mm x 1.65 mm



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Benefit by LTCC Multilayer Technology

High performance with easy matching.

➡ Integrated Optimum Matching for PA

Board real estate saving.

➡ Embedded Bare Chip IC, LPF, Matching



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LTCC Front End Module for .11b/g (3)

Characteristics

Parameter		Min.	Typ.	Max.	Unit	Condition
Small Signal [Ant -Rx]	IL	-	1.2	-	dB	f=2400 - 2500 MHz
	Input Return Loss	-	21	-	dB	f=2400 - 2500 MHz
	Output Return Loss	-	19	-	dB	f=2400 - 2500 MHz
Small Signal [Tx - Ant]	Gain	-	24	-	dB	f=2400 - 2500 MHz
	Gain Flattness	-	0.7	-	dB	f=2400 - 2500 MHz
	Input Return Loss	-	18	-	dB	f=2400 - 2500 MHz
	Output Return Loss	-	8	-	dB	f=2400 - 2500 MHz
	Current Consumption	-	130	-	mA	
Small Signal [Tx - Rx]	Isolation [PA: on]	-	2.3	-	dB	f=2400 - 2500 MHz
	1dB Compression Point	-	22.6	-	dBm	f=2450MHz
	Saturation Power	-	23.7	-	dBm	Pin= 7dBm, f=2450MHz
	Detector Output Voltage	-	0.2	-	V	Pout= 10dBm, f=2450MHz
	Detector Output Voltage	-	1.2	-	V	Pout= 20dBm, f=2450MHz
	Harmonic [2nd]	-	-66	-	dBc	Pout= 20dBm, f=4900MHz
	Harmonic [3rd]	-	-56	-	dBc	Pout= 20dBm, f=7350MHz
802.11b ACPR	Output Power	-	21	-	dBm	1st ACPR<-30dBc ,2nd ACPR<-50dBc ,f0=2447MHz
	Current Consumption	-	170	-	mA	1st ACPR<-30dBc ,2nd ACPR<-50dBc ,f0=2447MHz
OFDM [54Mbps, 64QAM]	Output Power	-	17	-	dBm	EVM = 5% ,f=2450MHz
	Current Consumption	-	139	-	mA	EVM = 5%



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3rd Topic

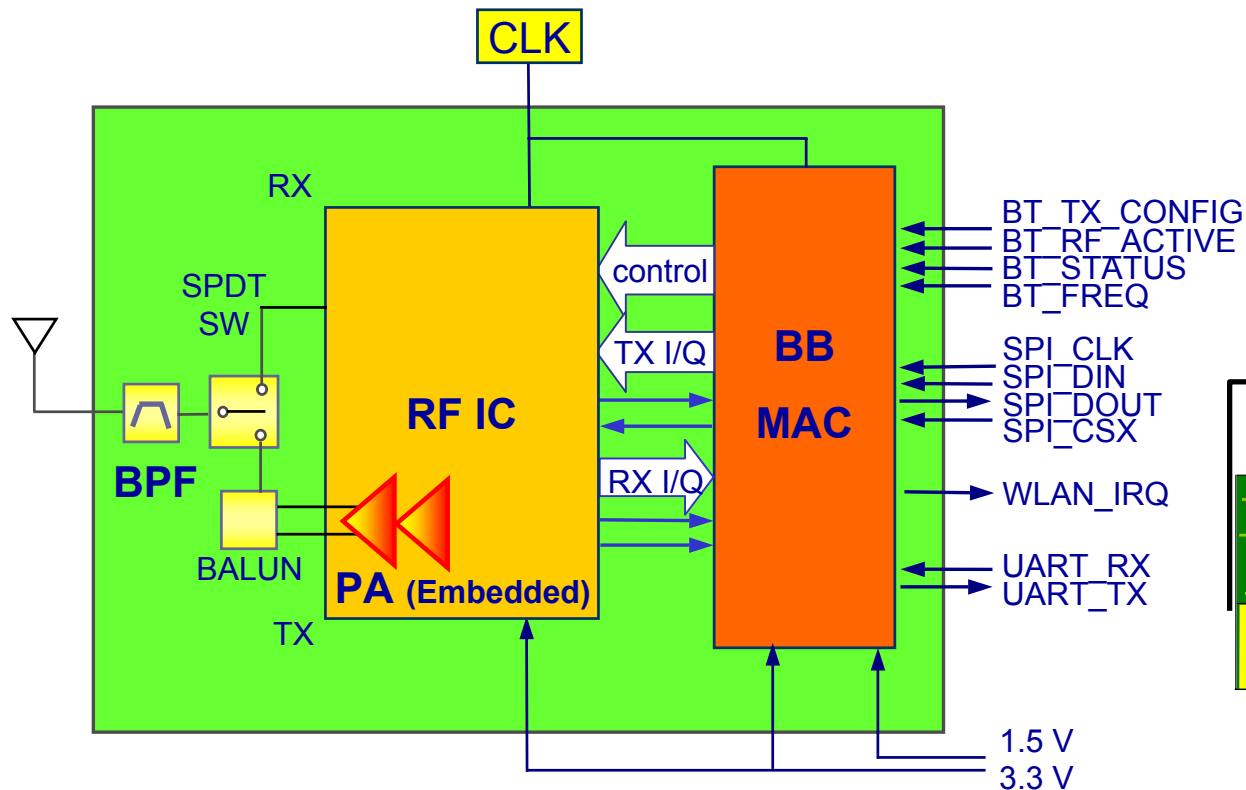
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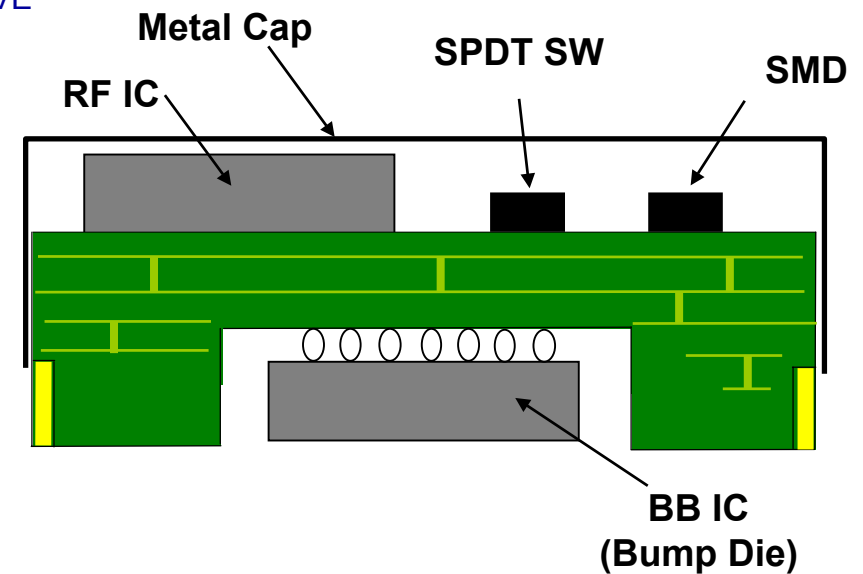
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LTCC .11b/g Module for Mobile Application

•Block Diagram



•Structure



9.6x9.6x1.8mm



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Final Topic

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To solve critical issues with Multilayer technology

Heat Dissipation

➡ Thermal Via

Blocking performance

➡ Integrated LC filter for Rx performance

Harmonics rejection

➡ Integrated LC filter for Tx performance

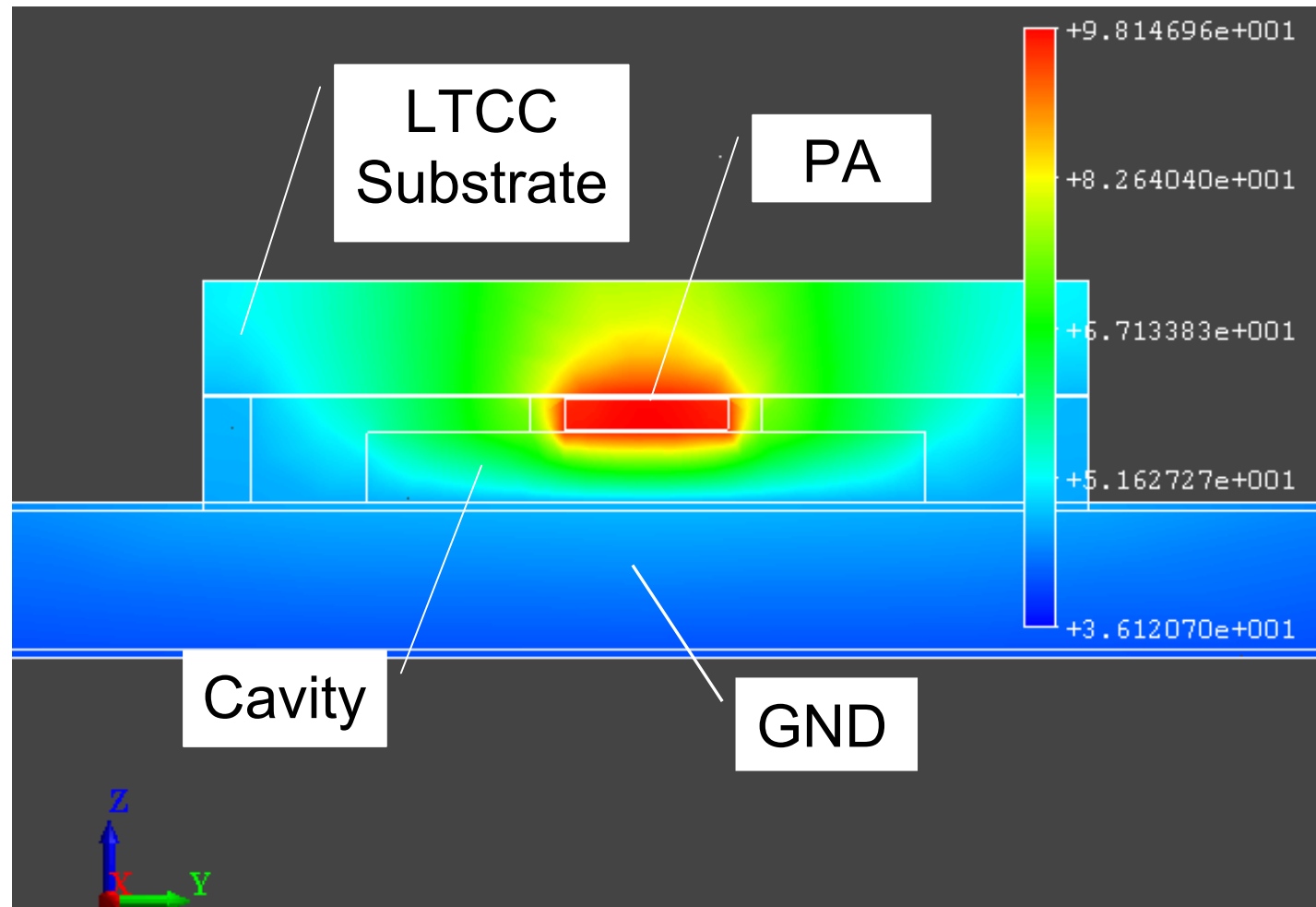
Height of Module

➡ Bumped Bare Chip IC

Drop Test

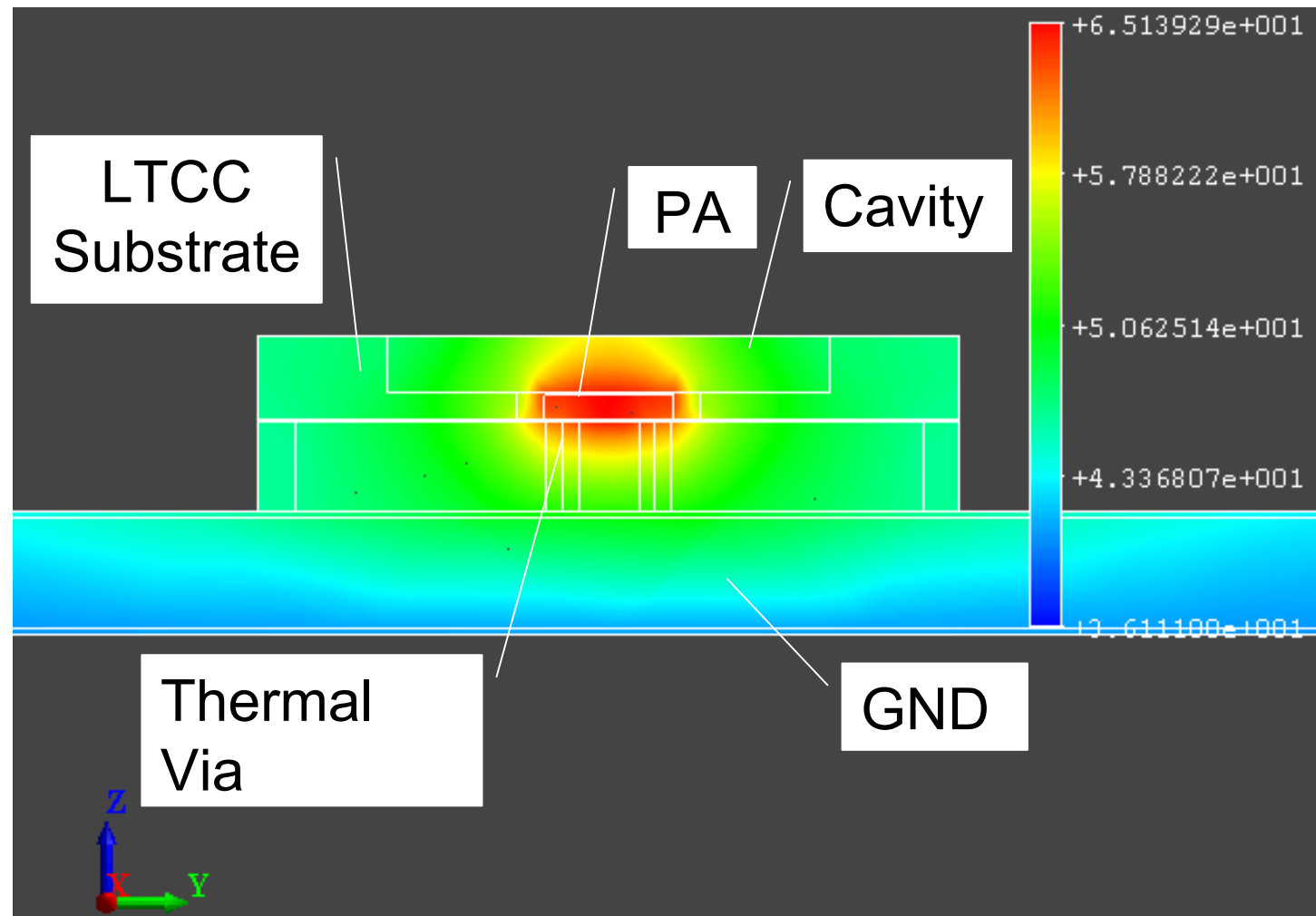
➡ Step up strength of Material

Thermal Simulation Result for Bottom Side Cavity



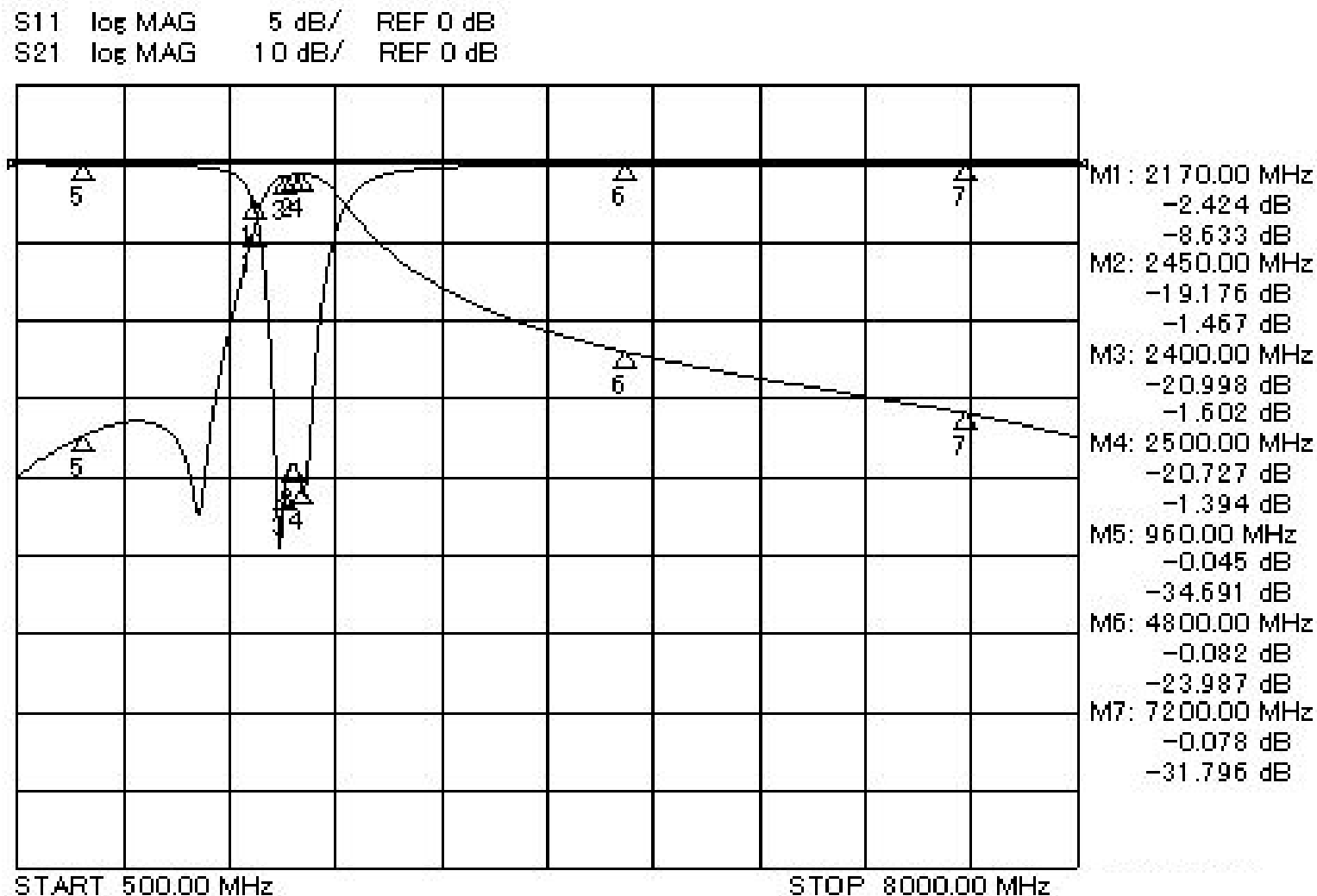
➤ The heat can't be escaped *without Thermal Via*

Thermal Simulation Result for Top Side Cavity



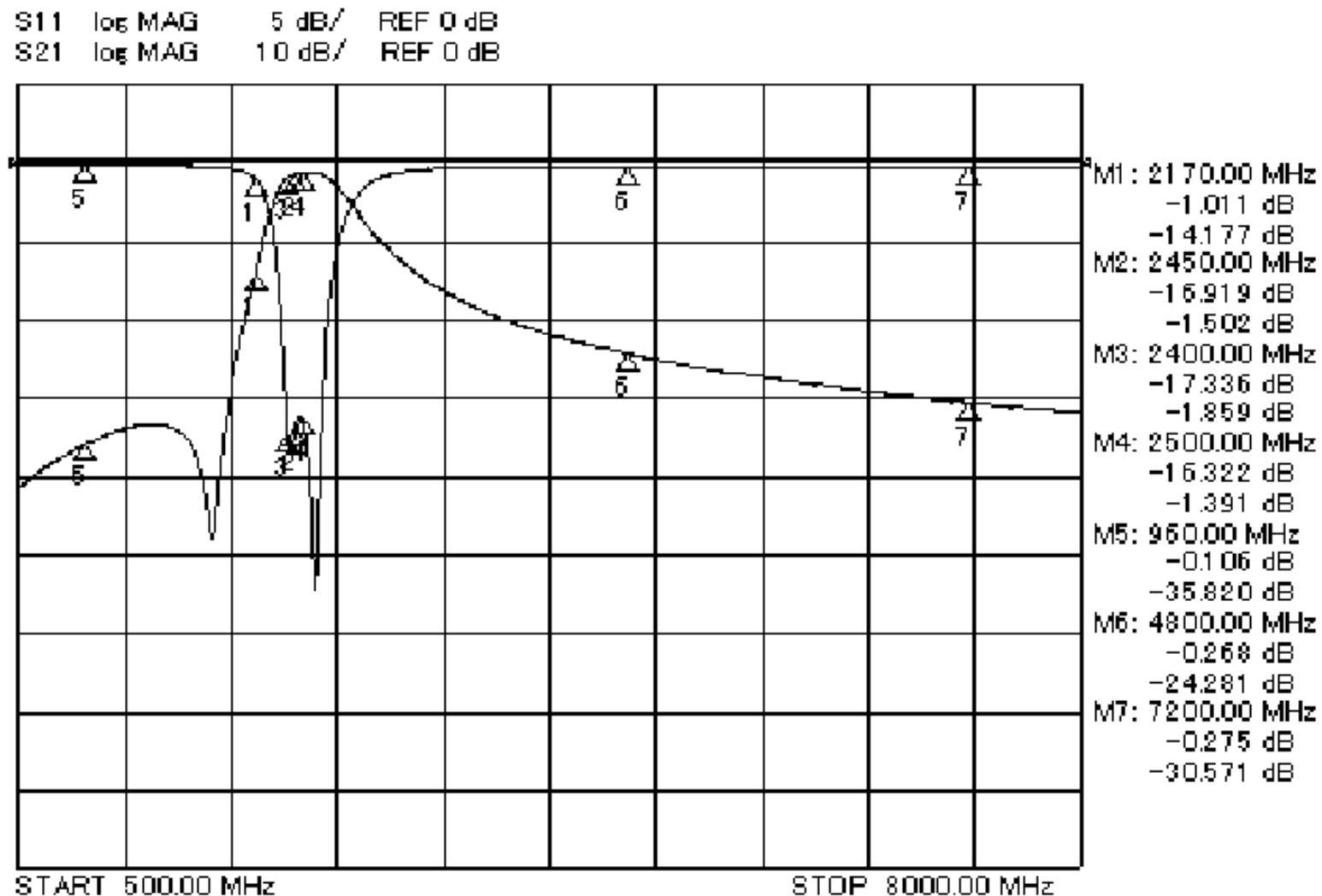
➤ The heat can be escaped *through Thermal Via*

Simulation Result of BPF performance



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Actual performance is same



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Benefit by using LTCC BPF

✓ Blocking Performance

Rejection performance for Mobile Tx Frequency

✓ Adjustable the Harmonics Distortion

Attenuation for High Frequency

✓ Size and Performance selectivity

Optimized for each RFIC and application



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Conclusion

➤ *Small Size*

Smallest module is come true by LTCC Multilayer Technology.
Passive components are built in LTCC substrate.

➤ *Provision for Heat issue*

Optimized the number of Via hole and the location is useful.

High Performance

Design of LTCC Multilayer BPF is very flexible.

**LTCC Multilayer technology is
very effective for smallest W-LAN module**



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